RoHS COMPLIANT

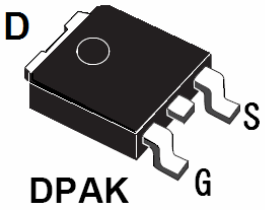
Description

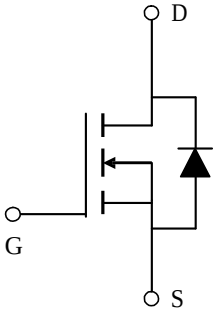
The XPX4080FD uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g. This device is ideal for high-frequency switching and synchronous rectification.

V_{DS} =40V,I_D =80A

$R_{DS(ON)}$=5.0mΩ (typ) @ V_{GS}=10V

$R_{DS(ON)}$=7.0mΩ (typ) @ V_{GS}=4.5V





General Features

- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 150 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
XPX4080	XPX4080FD	TO-252	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	80	A
Drain Current-Continuous(T_C=100℃)	I_D (100℃)	48	A
Pulsed Drain Current	I_{DM}	160	A
Maximum Power Dissipation	P_D	60	W
Debating factor		0.57	W/℃
Single pulse avalanche energy (Note 5)	E_{AS}	50	mJ
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55 To 175	℃
Thermal Resistance,Junction-to-Case (Note 2)	$R_{\theta JC}$	1.76	℃/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

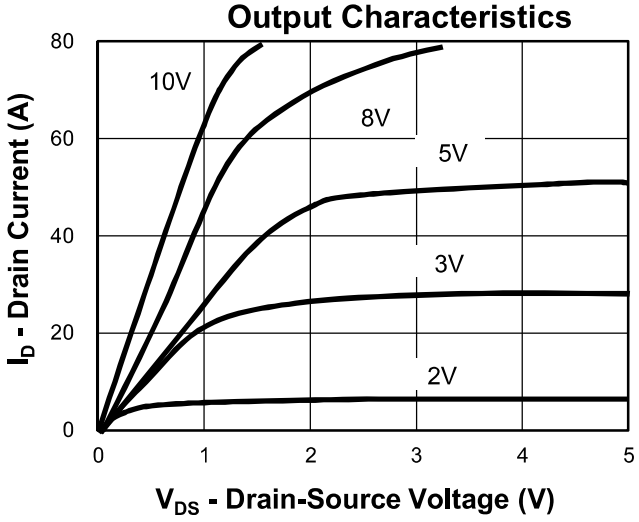
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=40V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	1	1.6	2.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=30A	-	5.0	7.0	mΩ
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=20A	30	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{lss}	V_{DS}=25V,V_{GS}=0V, F=1.0MHz	-	1650	-	PF
Output Capacitance	C_{oss}		-	171	-	PF
Reverse Transfer Capacitance	C_{rss}		-	115	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=20V,I_D=20A,R_L=1Ω V_{GS}=10V,R_{GEN}=3Ω	-	5.0	-	nS
Turn-on Rise Time	t_r		-	24	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	38	-	nS
Turn-Off Fall Time	t_f		-	12	-	nS
Total Gate Charge	Q_g	V_{DS}=30V,I_D=30A, V_{GS}=10V	-	24	-	nC
Gate-Source Charge	Q_{gs}		-	5.9	-	nC
Gate-Drain Charge	Q_{gd}		-	3.6	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=30A	-	-	1.2	V
Diode Forward Current (Note 2)	I_S		-	-	48	A
Reverse Recovery Time	t_{rr}	TJ = 25°C, IF =30A di/dt = 100A/μs (Note3)	-	9		nS
Reverse Recovery Charge	Qrr		-	15		nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

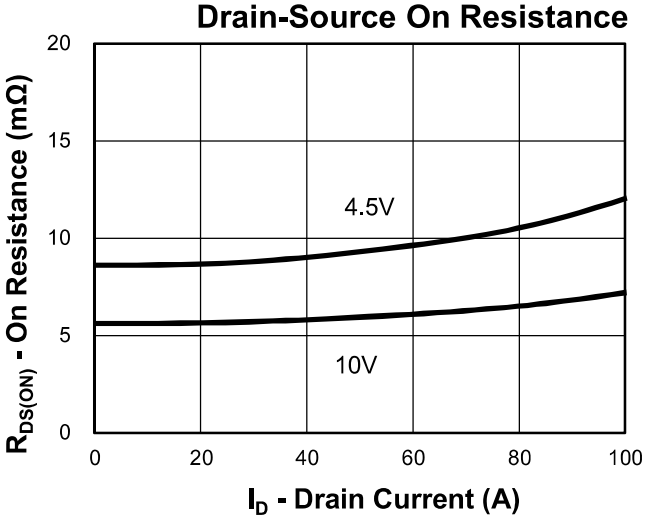
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. E_{AS} condition: Tj=25℃,V_{DD}=30V,V_G=10V,L=0.5mH,Rg=25Ω

Typical Characteristics

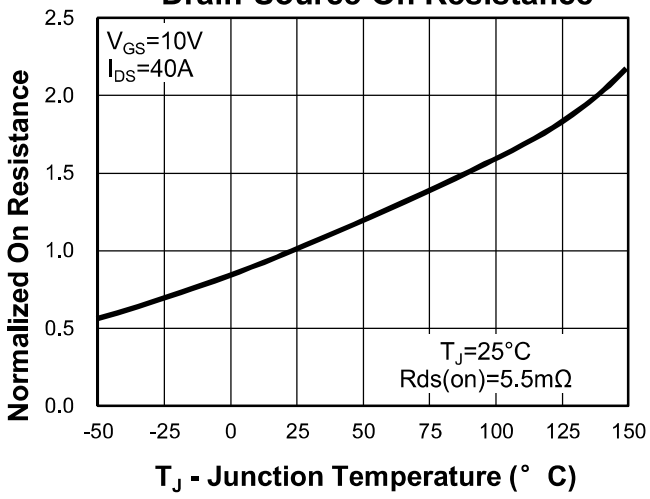
Output Characteristics



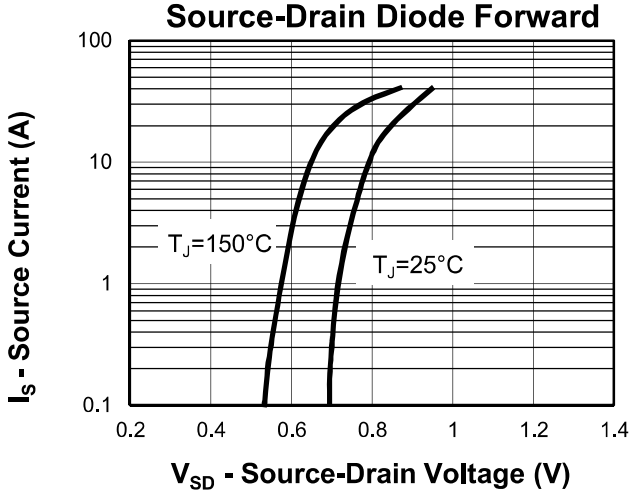
Drain-Source On Resistance



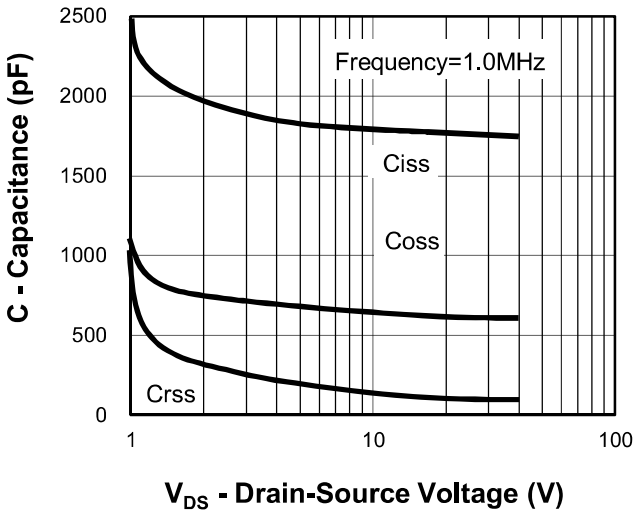
Drain-Source On Resistance



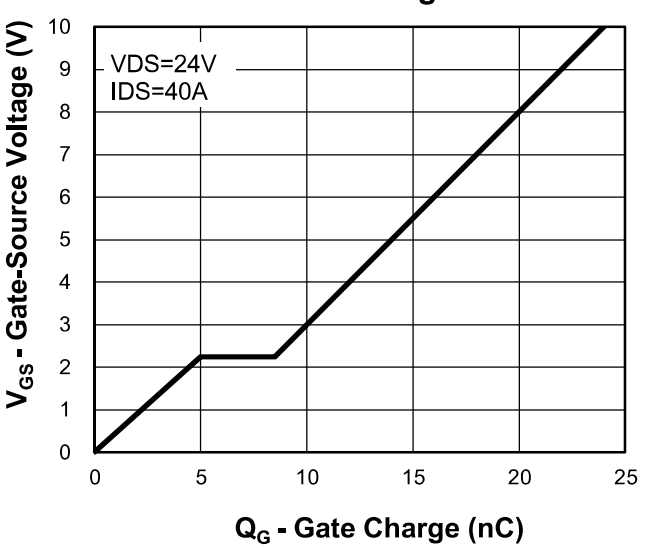
Source-Drain Diode Forward

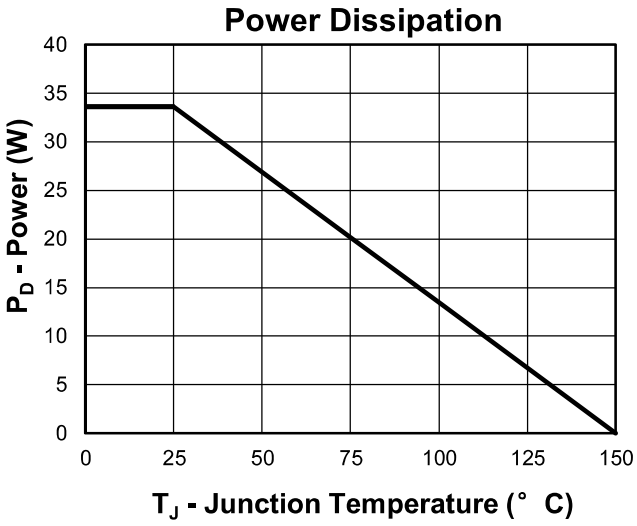


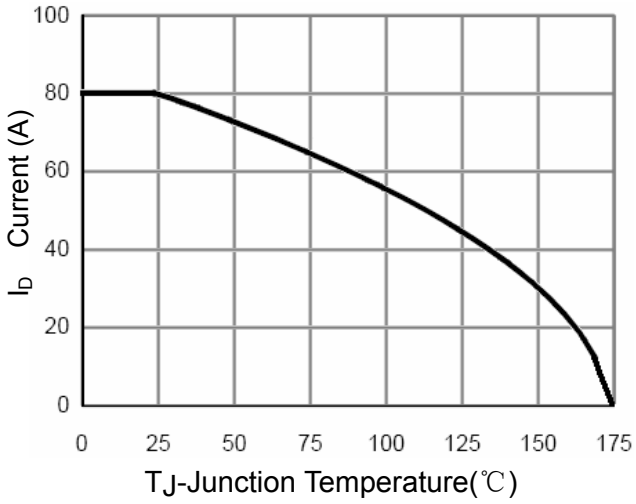
Capacitance

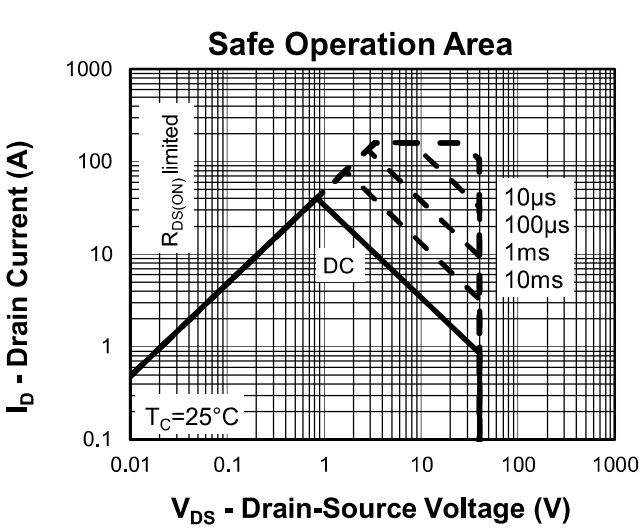


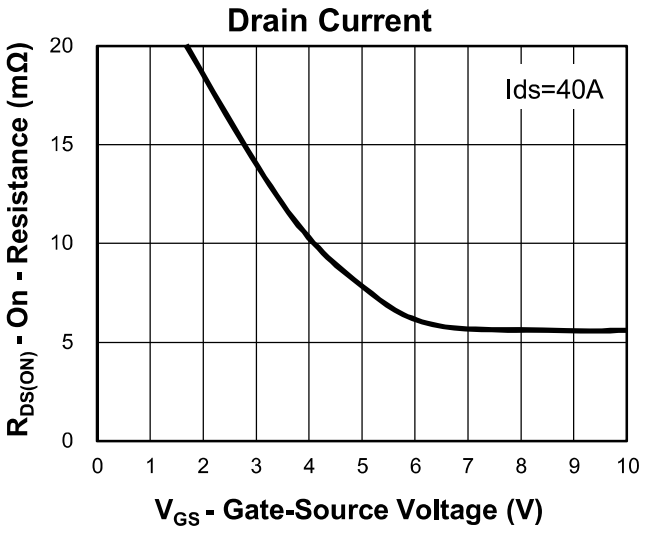
Gate Charge

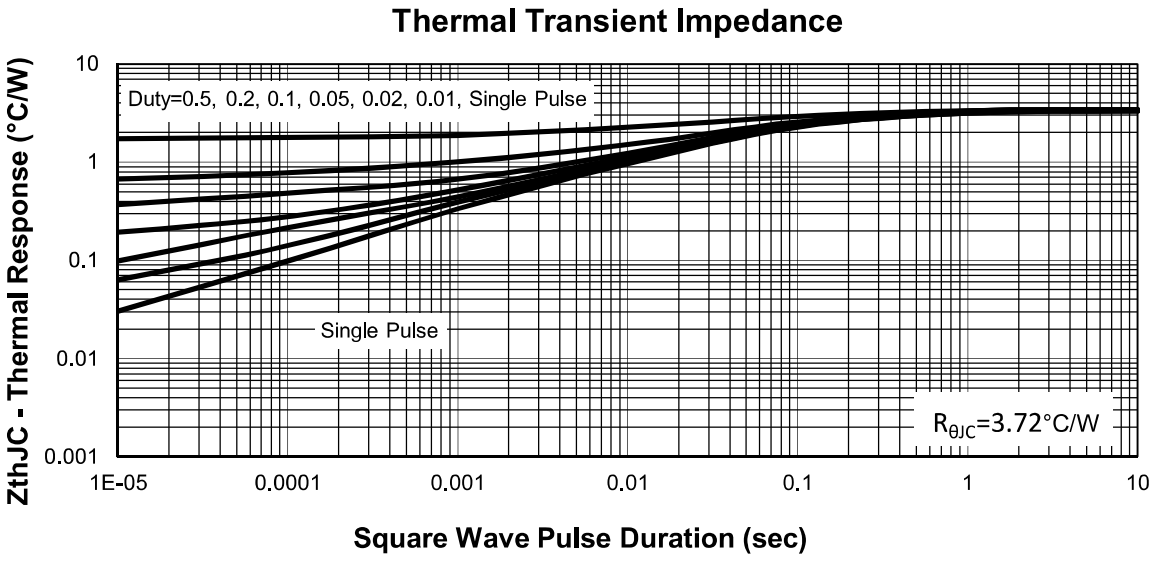



Power Dissipation
P_D - Power (W)
40
35
30
25
20
15
10
5
0
0
25
50
75
100
125
150
T_J - Junction Temperature (° C)

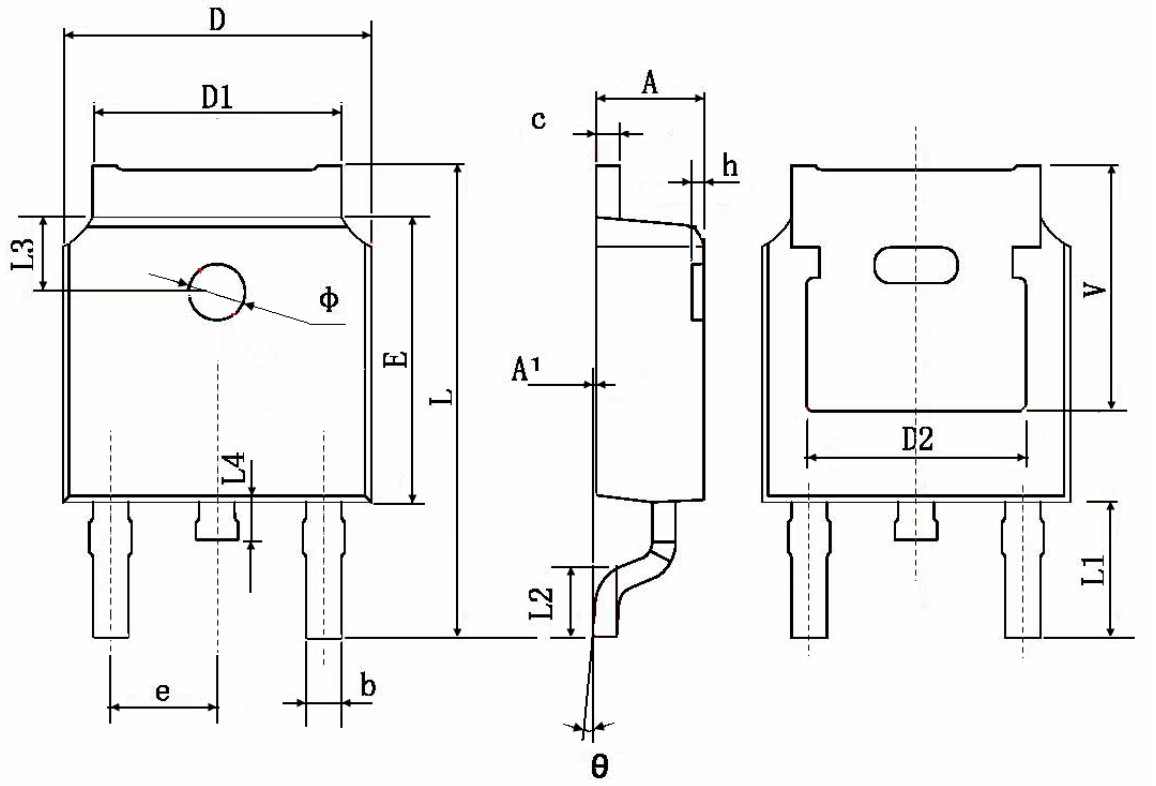

I_D Current (A)
100
80
60
40
20
0
0
25
50
75
100
125
150
175
TJ-Junction Temperature(℃)


Safe Operation Area
I_D - Drain Current (A)
1000
100
10
1
0.1
$R_{DS(ON)}$ limited
DC
10μs
100μs
1ms
10ms
T_C=25°C
0.01
0.1
1
10
100
1000
V_{DS} - Drain-Source Voltage (V)


Drain Current
$R_{DS(ON)}$ - On - Resistance (mΩ)
20
15
10
5
0
Ids=40A
0
1
2
3
4
5
6
7
8
9
10
V_{GS} - Gate-Source Voltage (V)


Thermal Transient Impedance
ZthJC - Thermal Response (°C/W)
10
1
0.1
0.01
0.001
Duty=0.5, 0.2, 0.1, 0.05, 0.02, 0.01, Single Pulse
Single Pulse
$R_{\theta JC}$=3.72°C/W
1E-05
0.0001
0.001
0.01
0.1
1
10
Square Wave Pulse Duration (sec)

TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

Flow (wave) soldering (solder dipping)

Product	Peak Temperature	Dipping Time
Pb device	245℃±5℃	5sec±1sec
Pb-Free device	260℃+0/-5℃	5sec±1sec

This integrated circuit can be damaged by ESD UniverChip Corporation recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedure can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Attention:

- Any and all XPX power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your XPX power representative nearest you before using any XPX power products described or contained herein in such applications.

- XPX power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all XPX power products described or contained herein.

- Specifications of any and all XPX power products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

- XPX power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

- In the event that any or all XPX power products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of XPX power Semiconductor CO.,LTD.

- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. XPX power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

- Any and all information described or contained herein are subject to change without notice due to product/ technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the XPX power product that you intend to use.

- This catalog provides information as of Sep.2019. Specifications and information herein are subject to change without notice.